

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAB3R9SN04C
Package Type :	PDFNWB3.3x3.3-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	4.33%
Lead Frame	Copper	7440-50-8	97.3420%	27.54%
	Iron	7439-89-6	2.4000%	
	Zinc	7440-66-6	0.1500%	
	Phosphorus	7723-14-0	0.1000%	
	Lead (Pb)	7439-92-1	0.0080%	
	Silver	7440-22-4	2.5000%	
Die Attach	Lead	7439-92-1	0.0275%	3.58%
	Tin	7440-31-5	0.1000%	
	Silver	7440-22-4	0.1250%	
	Butanediol mixture	107-88-0	99.6975%	
	Modified castor oil	61788-85-0	0.0500%	
Clip	Phosphorus	7723-14-0	83.4500%	9.49%
	Iron	7439-89-6	4.5000%	
	Zinc	7440-66-6	2.1500%	
	Copper	7440-50-8	8.5000%	
	Silver	7440-22-4	1.4000%	
Au Wire	Gold	7440-57-5	99.99%	8.55%
	Others	/	0.01%	
Mold Compound	Silica	60676-86-0	86.4500%	38.03%
	Epoxy Resin	29690-82-2	6.5000%	
	Phenol Resin	26834-02-6	6.5000%	
	Carbon black	1333-86-4	0.5500%	
Plating	Tin	7440-31-5	99.99%	8.48%
	Other	/	0.01%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.